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Haruta et al.

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[54] PRINTED CIRCUIT BOARD AND METHOD FOR MAKING THE SAME

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[57] ABSTRACT

A printed circuit board made by providing on an insulating substrate an adhesive coating comprising a butadiene-based rubber and a phenolic resin finely dispersed therein, etching the surface layer of said coating with an oxidizing agent to expose the microcapsules having phenolic resin shells, which have been formed during the setting of said adhesive coating, and forming a chemically deposited metal layer on said adhesive coating.

4 Claims, 6 Drawing Figures

